

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YOUN SOO SOHN	07/09/2019
YONG JOO JUN	07/09/2019
PRAKASH GOUDA AVAJI	07/09/2019
RECEIVING PARTY DATA	
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City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16430244
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NAME OF SUBMITTER:	LEEVI OLIVIER
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DATE SIGNED:	07/12/2019
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, I, as a below named inventor, am a joint inventor of certain new and useful improvements in NOVEL CATIONIC POLYPHOSPHAZENE COMPOUND, POLYPHOSPHAZENES-DRUG CONJUGATE COMPOUND AND METHOD FOR PREPARING SAME for which U.S. Patent Application was filed as application number 16/430,244, on June 3, 2019.

AND WHEREAS, CNPHARM CO., LTD., a limited partnership, with offices at Daehyeon-dong, B-455, 52, Ewhayeodae-gil, Seodeamun-gu, Seoul, Korea (South) (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any prior applications and any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or their designee(s), as ASSIGNEE or their successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at their own expense;

And I further agree that ASSIGNEE will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment executed on the dates indicated below.

Youn Soo Sohn
Name of first inventor

Hundae Apartment 8th 93-dong No. 1003, Apgu, 201ng-ro 309, Gangnam-gu,
Residence of first inventor Seoul, Korea

[Signature]
Signature of first inventor

July 9, 2019
Date of Assignment

Yong Joo Jun

Name of second inventor

Saotjeon Apartment 201-dong No. 102, Myeonggil-ro 316, Gangdong-gu, Seoul, Korea
Residence of second inventor

Yong Joo Jun
Signature of second inventor

9 July, 2019
Date of Assignment

Prakash Gouda Avaji

Name of third inventor

Artville No. 102, Seongsan-ro 24-gil 26, Seodaemun-gu, Seoul, Korea
Residence of third inventor

Prakash Gouda Avaji
Signature of third inventor

9th July 2019
Date of Assignment